

Table of Contents

Preface and Committees

The Rinsing Problem: Effect of Solute-Surface Interactions on Wafer Purity L.M. Loewenstein and P.W. Mertens	1
Hydrogenated Ultrapure Water Production System for Future Wet Cleaning Process H. Morita, J.i. Ida, T. Mizuniwa and T. Ohmi	7
Behaviour of Metallic Contaminants during Mos Processing T. Bearda, S. De Gendt, L.M. Loewenstein, M. Knotter, P.W. Mertens and M. Heyns	11
Hydrogen Peroxide Decomposition in Ammonia Solutions D.M. Knotter, S. De Gendt, M. Baeyens, P.W. Mertens and M. Heyns	15
New Aspects of the Diluted Dynamic Clean Process F. Tardif, T. Lardin, A. Maciejny, A. Danel, P. Boelen, C. Cowache, I. Kashkoush and R. Novak	19
Single Step Alkaline Cleaning Solution for Advanced Semiconductor Cleaning M. Baeyens, W. Hub, B.O. Kolbesen, A.R. Martin and P.W. Mertens	23
Particle Removal Efficiency and Silicon Roughness in HF-DIW/O₃/Megasonics Cleaning M. Alessandri, E. Bellandi, F. Pipia, F. Cazzaniga, K. Wolke and M. Schenkl	27
Industrial Trends in Wet Processing Technology L.F.T. Kwakman, M. Geomini, D. Lévy and D. Malgouyres	31
Particle Addition Behaviour of Oxide Stripping by HF Solutions E. Bellandi, M. Alessandri, F. Pipia and A. Tonti	35
The Electrochemical Kinetics of Silicon Surface Corrosion in HF Containing Dilute Solutions V. Bertagna, F. Rouelle, R. Erre and M. Chemla	39
Influence of the Dissolved Gas in Cleaning Solution on Silicon Wafer Cleaning Efficiency H. Kanetaka, T. Kujime, H. Yazaki, T. Kezuka and T. Ohmi	43
Optimization of Deionized Water Consumption in Wafer Wet Processing I. Kashkoush and R. Novak	49
Chemistry of the Silicon Oxide Surface: Adsorption from SC1 Solutions L. Hall, J. Sees, T. Hurd, B. Schmidt, L. Bellay, L.M. Loewenstein and P.W. Mertens	53
Production of High Concentrations of Bubble-Free Dissolved Ozone in Water C. Gottschalk, U. Beuscher, S. Hardwick, M. Kobayashi, J. Schweckendiek and M. Wikol	59
Si-Purifier: A Point of Use Purifier for Noble Metals in HF Baths A. Beverina and F. Tardif	63
Potassium Adhesion to Various CVD Oxide and the Surface Cleaning with Hot UPW T. Jizaimaru, H. Kanetaka, S. Omae and T. Ohmi	67
Production Performance of Single Tank Cleaning Processes for 0,25 µm Technology K. Penner, K. Schupke, R. Pesce, J. Oshinowo and K. Wolke	71
Ozonated DI-Water for Clean Chemical Oxide Growth I. Cornelissen, M. Meuris, K. Wolke, M. Wikol, L.M. Loewenstein, G. Doumen and M. Heyns	77
Ultra-Thin Oxide Growth on Silicon Using Ozonated Solutions F. De Smedt, C. Vinckier, I. Cornelissen, S. De Gendt, M. Meuris, G. Gilis and M. Heyns	81
Gas-Phase Surface Processing Prior to 3.2 nm Gate Oxidation J. Ruzyllo, E. Röhr, M. Baeyens, T. Bearda, P.W. Mertens and M. Heyns	85
Post Dry-Etch Cleaning Issues of an Organic Low-K Dielectric F. Lanckmans, M.R. Baklanov, C. Alaerts, S. Vanhaelemeersch and K. Maex	89
Vapor Phase Decomposition - Droplet Collection: Can we Improve the Collection Efficiency for Copper Contamination? S. De Gendt, A. Huber, B. Onsia, S. Arnauts, K. Kenis, D.M. Knotter, P.W. Mertens and M. Heyns	93
Characterization of the Post Dry Etch Cleaning of the Silicon Surface Prior to Silicon Epitaxial Growth Y.B. Kim, M. Caymax, H. Bender and S. Vanhaelemeersch	97
Silicon Contamination Prevention in HF Mixtures V. Bertagna, F. Rouelle, R. Erre and M. Chemla	101

Applications of Tetramethylammonium Hydroxide (TMAH) as a Post Tungsten CMP Cleaning Mixture M. Jolley	105
Fe and Cu Removal Efficiency in HF-DIW/O₃ Cleaning Sequence F. Pipia, E. Bellandi, B. Crivelli and M. Alessandri	109
Post Polysilicon Etch (Incorporating DUV Resist an BARC) Polymer Cleaning S.Y.M. Chooi, P. Ee, B.-. Seah and M.S. Zhou	113
Determination of Moisture / Water in Semiconductor Processing Liquids On-Line with the SemiChem Process Analyzer J.H. Evans-Freeman, G. Frank and P.M. Robertson	117
Evaluation of Cleaning Recipes Based on Ozonated Water for Pre-Gate Oxide Cleaning J.S. Jeon, B. Ogle, M. Baeyens and P.W. Mertens	119
Characterization of Emitter Interface Oxide Growth in a Vertical LPCVD Polysilicon Deposition Reactor M. Ramin, C. Hechtel and A. Haeusler	123
Nitride Strip: Phosphoric Acid Bath-Life above 100 Hours C. Willis	127
Wet Metal Etching for Ti/Co Self-Aligned Silicides S. O'Brien	131
Post-Titanium-Salicide Cleaning with Spray Technology J. Diedrick, A. Mauri and V. Nguyen	135
XPS Study of the Cleaning Efficiency by Ozone Processes of the Protective Films Formed by Reactive Ion Etching of Co and Ti Silicide T. Conard, S. De Gendt, M.R. Baklanov, R. Vos, M. Heyns and W. Vandervorst	139
Plasma Etch Residue and Photoresist Removal Utilizing Environmentally Benign Process Chemicals W. Kleemeier, V. Leon and S. Graham	143
Angle Resolved XPS Characterization of the Formation of Cl and Br Bonds in Poly-Silicon Etching and Its Cleaning Y.B. Kim, B. Beckx, S. Vanhaelemeersch and W. Vandervorst	153
Dynamics of Mass Transfer on a Wafer Surface in Ozonated-Water Processing for Photoresist Removal N. Narayanswami and S. Nelson	157
Construction of the Distribution System for Ozonized Water Used in the Wet Cleaning of Si Wafer Surface O. Nakamura, M. Yoshida, Y. Shirai, M. Nagase, M. Kitano, M. Gozyuki, Y. Hashimoto and T. Ohmi	161
A Novel Resist and Post-Etch Residue Removal Process Using Ozonated Chemistry S. De Gendt, P. Snee, I. Cornelissen, M. Lux, R. Vos, P.W. Mertens, D.M. Knotter, M.M. Meuris and M. Heyns	165
Post CMP Cleaning Using a Novel HF Compatible High Power Megasonic Tank F. Tardif, T. Lardin, I. Constant, M. Fayolle, P. Boelen, C. Cowache, I. Kashkoush and R. Novak	169
Relation between Oxide-CMP Induced Defects and Post-CMP Cleaning Strategies K. Devriendt, E. Vrancken, N. Heylen, J. Grillaert, M. Meuris, M. Heyns and Z.C. Lin	173
Evaluation of Post Metal Etch Cleaning by Analyzing the Chemical Compositions and Distributions on the Etched Al Surface H.L. Li, M.R. Baklanov, W. Boullart, T. Conard, B. Brijs, W. Vandervorst, K. Maex and L. Froyen	177
New Methods for Contamination Control and Dry Cleaning of Silicon Wafers G.S. Selwyn	181
Wafer Backside Cleaning by Twin-Fluid Flow Cleaning Y. Tatehara, K. Kitagawa, K. Shimada and E. Ando	183
Evaluation of a Dry Laser Cleaning Process for the Removal of Surface Particles G. Vereecke, E. Röhr and M. Heyns	187
Dependency of Micro Particle Adhesion of Dispersive and Nondispersive Interactions Analyzed by Atomic Force Microscopy A. Kawai, K. Shimada and E. Andoh	191

Integrated Cleaning: Application of Densified Fluid Cleaning (DFC) to Post-Etch Residue Removal	195
V. Starov, D. Beery and A. Kabansky	
Application of Microcalorimeter EDS X-Ray Detectors to Particle Analysis	199
A.C. Diebold, D.A. Wollman, G.C. Hilton, K.D. Irwin, J.M. Martinis and B.Y.H. Liu	
Surface Characterization in the Silicon Cleaning Process by a-UPC; Atmospheric Ultraviolet Photoelectron Counting	203
Y. Kôzuki, Y. Nakajima, T. Sato, K. Kinoshita and T. Tsunoda	
Microscopic Analysis of Particle Removal by Gas/Liquid Mixture High-Speed Flow	207
N. Hirano, K. Takayama, J. Falcovitz, T. Kataoka, K. Shimada and E. Ando	
Kelvin-SPV Measurements of Atomically-Flat Si(111) Surfaces Contaminated with Metallic Ions	211
T. Tagawa and T. Okumura	
Comparison of Analytical Methods for Residue Detection of Resist Removal Processes	215
T. Riihisaari, J. Likonen, A. Kiviranta, S. Eränen, S. Lehto, J. Tuominen, T. Lindblom and E. Muukkonen	
Dry Cleaning Technologies Using UV-Excited Radicals and Cryogenic Aerosols	219
T. Ito and R. Sugino	
A New HF Vapor Process for Native Oxide Removal, Suited for Cluster Applications	225
A.B. Storm, H. Sprey, J.W. Maes, E. Granneman, R. de Blank, E. Röhr, M. Caymax and M. Heyns	
Silicon Surface Cleaning for Low Temperature Silicon Epitaxial Growth	229
M. Mayuzumi, M. Imai, S. Nakahara, K. Inoue, J. Takahashi and T. Ohmi	
Role of UV/Chlorine Exposure during Dry Surface Conditioning before Integrated Epi Deposition Process	233
J. Ruzyllo, E. Röhr, M. Caymax, M. Baeyens, T. Conard, P.W. Mertens and M. Heyns	
Electrical Evaluation of the Epi/Substrate Interface Quality after Different In-Situ and Ex-Situ Low-Temperature Pre-Epi Cleaning Methods	237
M. Caymax, S. Decoutere, E. Röhr, W. Vandervorst, M. Heyns, H. Sprey, A.B. Storm and J.W. Maes	
Energy Loss of O1s Photoelectrons in Compositional and Structural Transition Layer at and near the SiO₂/Si Interface	241
H. Nohira, K. Takahashi and T. Hattori	
Metal Enhanced Oxidation of Silicon	245
M. Börner, N. Junghans, S. Landau and B.O. Kolbesen	
Effect of Si Surface Roughness on the Current-Voltage Characteristics of Ultra-Thin Gate Oxides	249
M. Houssa, T. Nigam, P.W. Mertens and M. Heyns	
Infrared Absorption Studies of Wet Chemical Oxides: Thermal Evolution of Impurities	253
Y.J. Chabal, M.K. Weldon, A.B. Gurevich and S.B. Christman	
X-Ray Photoelectron Study of Gate Oxides and Nitrides	257
R.L. Opila, J.P. Chang, M. Du, J. Bevk, Y. Ma, M. Weldon, Y. Chabal and A.B. Gurevich	
Evaluation of C₃F₈ as an In-Situ Cleaning Gas for PECVD Tools	261
R. Van San and L. Zazera	
Generation at Point-of-Use of BHF	267
S. Verhaverbeke and L.H. Liu	
Characterization of HF Cleaning of Ion-Implanted Si Surfaces	271
E. Kondoh, M.R. Baklanov and K. Maex	
Determination of SC1 Etch Rates at Low Temperatures with Microscope Interferometry	275
W. Storm, H.A. Gerber, G.-. Hohl, M. Naujok and R. Schmolke	
Impact of Trace Metals in Litho Chemicals	279
R. Vos, M. Lux, M. Meuris, P.W. Mertens, M. Heyns and R. Ramage	
Post Metal Etch Polymer Removal: An Investigation of Parameters that Influence Corrosion	283
W. Boullart, G. Mannaert, S. Graham, C. Tarassenko and L. Mouche	
A Process Using Ozonated Water Solutions to Remove Photoresist after Metallization	287
S.L. Nelson and L.E. Carter	

**The Optimization of the Cleaning to Remove Residual Bonds of Si-C and Si-F after
Fluorocarbon Plasma Etch on the Silicon Surface**

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291